

Filename: PMP7170_REVB BOM_bom.xls

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PMP7170_REVB BOM BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C3	10pF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
1	C17	1500pF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
1	C18	33nF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
1	C56	68nF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
8	C1 C4 C10 C32 C34 C40 C42 C48	0.1uF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
2	C13 C51	10uF	Capacitor, Ceramic Chip, 16V, ±10%	1210	Std	STD
2	C14 C52	1uF	Capacitor, Ceramic Chip, xxV, ±10%	1206	STD	STD
2	C15 C53	470uF	Capacitor, Aluminum, 6.3V, 20%	5 x 11mm	EKZM6R3ELL471	Panasonic
2	C16 C54	10uF	Capacitor, Ceramic Chip, 6.3V, ±10%	0805	STD	STD
3	C2 C33 C41	22uF	Capacitor, Ceramic Chip, 16V, ±10%	1210	Std	STD
4	C36-37 C46 C6	22uF	Capacitor, Ceramic Chip, xxV, ±10%	1210	Std	STD
2	C47 C7	TBD	Capacitor, Ceramic Chip, xxV, ±10%	1210	Std	STD
2	C50 C12	0.01uF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
3	C8 C38 C44	1uF	Capacitor, Ceramic Chip, xxV, ±10%	0805	STD	STD
4	C9 C39 C45 C55	3300pF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
10	J1-4 J11-16	TBD	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25		OST
1	L1	3.3uH	Inductor, SMT, yyA, zzmilliohm	0.402 x 0.394 in	MSS1048-xxxL	Coilcraft
1	L2	6.8uH	Inductor, SMT, yyA, zzmilliohm	0.402 x 0.394 in	MSS1048-xxxL	Coilcraft
1	L4	1.5uH	Inductor, SMT, yyA, zzmilliohm	0.402 x 0.394 in	MSS1038-xxxNX	Coilcraft
1	L5	2.5uH	Inductor, SMT, yyA, zzmilliohm	0.402 x 0.394 in	MSS1038-xxxNX	Coilcraft
1	L6	5.2uH	Inductor, SMT, yyA, zzmilliohm	0.402 x 0.394 in	MSS1038-xxxNX	Coilcraft
1	R1	123k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R3	22.6k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R7	49.9k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R8	10k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R10	15.8k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R27	8.25k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R31	30.1k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R37	24.9k	Resistor, Chip, 1/16W, x%	0603	Std	Std

1	R38	4.99k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R40	28.0k	Resistor, Chip, 1/16W, x%	0603	Std	Std
5	R2 R5 R28 R32 R35	100k	Resistor, Chip, 1/16W, x%	0603	Std	Std
2	R29 R33	22.1k	Resistor, Chip, 1/16W, x%	0603	Std	Std
2	R6 R36	49.9	Resistor, Chip, 1/16W, x%	0603	Std	Std
8	TP1-4 TP15-18	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 in	5000	Keystone
2	TP5 TP19	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 in	5001	Keystone
1	U1	TPS54429EPWP	IC, 4.5V to 18V Input, 4-A Synchronous Step-D	HTSSOP	TPS54426PWP	TI
2	U2 U6	TPS54521RHL	IC, 17V Input, 5A Output, Sync. Step Down Sw	QFN14	TPS54521RHL	TI
2	U4-5	TPS54326PWP	IC, 3-A Output Single Sync. Step-Down Switch	HTSSOP-14	TPS54325PWP	TI

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk ('**') cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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